




Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	24-03-2020
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement			
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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H735ZGT6	E11A*483XXXZ	A	9991	24-03-2020
	Amount	UoM	Unit type	ST ECOPACK Grade
	1315.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LQFP	20X20X1.4	144		
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-16th July 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	E11A*483XXXZ				6000000.0	999999.6
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	13.690	mg	supplier	die	Silicon (Si)	7440-21-3		13.190	mg	963477	10030
				supplier	metallization	Aluminium (Al)	7429-90-5		0.059	mg	4310	45
				supplier	metallization	Copper (Cu)	7440-50-8		0.186	mg	13587	141
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	73	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.030	mg	2191	23
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	365	4
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	73	1
				supplier	Passivation	Silicon Oxide	7631-86-9		0.218	mg	15924	166
Leadframe LF# C7025		360.500	mg		Leadframe	Copper (Cu)	7440-50-8		340.312	mg	944000	258792
					Leadframe	Silver (Ag)	7440-22-4		5.408	mg	15000	4112
					Leadframe	Magnesium (Mg)	7439-95-4		0.631	mg	1750	480
					Leadframe	Silicon (Si)	7440-21-3		2.614	mg	7250	1988
					Leadframe	Nickel (Ni)	7440-02-0		11.536	mg	32000	8773
Glue (CRM 1076WA)		2.800	mg		Glue or tape	Silver Powder	7440-22-4		2.111	mg	754000	1605
					Glue or tape	Bisphenol F Type Epoxy Resin	9003-36-5		0.084	mg	30000	64
					Glue or tape	Epoxy resin	Trade Secret		0.196	mg	70000	149
					Glue or tape	Diluent	Trade Secret		0.070	mg	25000	53
					Glue or tape	Ethylene dimethacrylate	97-90-5		0.224	mg	80000	170
					Glue or tape	1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0		0.084	mg	30000	64
					Glue or tape	Dicyandiamide	461-58-5		0.015	mg	5500	12
					Glue or tape	1,1-Di(t-butylperoxy)cyclohexane	3006-86-8		0.015	mg	5500	12
Bonding wire (Au 0.8 mils)		5.000	mg		Bonding wire	Au	7440-57-5		4.943	mg	988500	3759
					Bonding wire	Palladium	7440-05-3		0.058		11500	44
Encapsulation (Sumitomo,EME-G631SH)		912.109	mg		Molding Compound	Epoxy Resin A	Proprietary		18.242	mg	20000	13872
					Molding Compound	Epoxy Resin B	Proprietary		18.242	mg	20000	13872
					Molding Compound	Phenol Resin	Proprietary		50.166	mg	55000	38149
					Molding Compound	Carbon Black	1333-86-4		5.017	mg	5500	3815
					Molding Compound	Silica(Amorphous) A	60676-86-0		683.626	mg	749500	519867
External Plating		20.900	mg		Molding Compound	Silica(Amorphous) B	7631-86-9		136.816	mg	150000	104043
					Matte Sn	Tin (Sn)	7440-31-5		20.898	mg	999900	15892
					Matte Sn	Impurities	Proprietary		0.002	mg	100	2